

3H-02 Strategies toward Low-Cost CC

- High-rate fabrication methods (substrate & HTS)
- Innovative approaches to CC cost reduction
- Quality control to maximize CC throughput
- Strategies to increase CC yield

3H-02 Q & A

- \$30/kA-m target (Yamada)
 - Wire cost = (S + B + HTS + Stabilizers)/Current
 - <\$5 for HTS (Moeckly); <\$1 for (Ni-alloy)(Selva); \$30 (HTS \$16+ Template \$ 12) (ISTEC)
- Wider (RABiTS) vs. multi-turn (IBAD) tapes?
 - Uniformity; IBAD limitation; Process specific; tension issues; ROEBEL (needs > 12 mm wide); FCL; Transformers (< 12 mm)
- F-based MOD vs. non-F process?
 - > 1.5 $\mu\text{m}/\text{coat}$; pyrolysis time; Laser; MOCVD precursors
- HTS (RCE: \$ 5/kA-m; 500 A/cm; 2 μm)
- On-line monitoring